

In the Specification:

At pages 12-13, please rewrite the entire section of this application entitled BRIEF DESCRIPTION OF THE DRAWINGS as follows:

BRIEF DESCRIPTION OF THE DRAWINGS

~~FIG. 1 shows~~ FIGS. 1A, 1B and 1C show cross-sectional diagrams of an ink jet head according to an embodiment of the present invention;

~~FIG. 2 shows~~ FIGS. 2A, 2B and 2C show cross-sectional diagrams of an ink jet head module connected with a driving IC according to the embodiment of the present invention shown in FIGS. 1A – 1C;

~~FIG. 3 shows~~ FIGS. 3A and 3B show explanatory diagrams illustrating a method of manufacturing the ink jet head according to the embodiment of the present invention shown in FIGS. 1A – 1C;

~~FIG. 4 shows~~ FIGS. 4A and 4B show explanatory diagrams illustrating ~~the same~~ further steps of the method of FIGS. 3A – 3B;

~~FIG. 5 shows~~ FIGS. 5A and 5B show explanatory diagrams illustrating ~~the same~~ further steps of the method of FIGS. 3A – 3B;

~~FIG. 6 shows~~ FIG. 6A, 6B and 6C show cross-sectional diagrams of an ink jet head according to a different embodiment of the invention;

~~FIG. 7 shows~~ FIG. 7A, 7B and 7C show cross-sectional diagrams of an ink jet head module connected with a driving IC according to the ~~different~~ embodiment of FIGS. 6A – 6B;

FIG. 8 is a cross-sectional diagram of an ink jet head according to another embodiment of the invention;

FIG. 9 is a cross-sectional diagram of an ink jet head module connected with a driving IC according to ~~this second~~ the embodiment of the invention of FIG.8;

~~FIG. 10 shows~~ FIGS. 10A and 10B show explanatory diagrams illustrating a method of manufacturing the ink jet head according to ~~this second~~ the embodiment of the invention of FIG. 8;

~~FIG. 11 shows~~ FIGS. 11A and 11B show explanatory diagrams further illustrating the ~~same~~ method of FIGS. 10A –10B;

~~FIG. 12 shows~~ FIGS. 12 A and 12B show explanatory diagrams further illustrating the ~~same~~ method of FIGS. 10A –10B;

FIG. 13 is a cross-sectional diagram illustrating one example of a conventional ink jet head;

~~FIG. 14 shows an~~ FIGS. 14A, 14B and 14 B show explanatory ~~diagram~~ diagrams illustrating a method of manufacturing the conventional ink jet head;

FIG. 15 is a cross-sectional diagram illustrating a different example of a conventional ink jet head; and

~~FIG. 16 shows~~ FIGS. 16A, 16B and 16C show cross-sectional diagrams illustrating another example of a conventional ink jet head

Please rewrite the paragraph bridging pages 16 and 17 as follows:

This ink jet head can be electrically and mechanically connected to outer leads 52 formed on a TAB tape 51 (see FIGS. 2A – 2C), the outer leads 52 being connected to a driving IC 50, at the electrically conductive resin electrodes 11 at the rear end portion 21 of the actuator 20 via ACF (anisotropic conductive film) 53 as shown in ~~FIG. 2~~ FIGS. 1B and 2B. Although not illustrated in detail, the ACF 53 is made essentially of an epoxy resin binder which is stable in the B stage containing dispersed electrically conductive particles formed of plastic particles measuring 5 μ m in diameter of which the surfaces are plated with nickel (Ni) and gold (Au).

Please rewrite the first full paragraph on page 32 and the paragraph bridging pages 32 and 33 as follows:

While the areas of the electrically conductive resin electrodes 11 later exposed on the cut surface of each segmented ink jet head are increased by filling the electrically conductive resin 10 into the grooves deeper than the ink chambers 22, the same effect is expected to be achieved by forming wide grooves 27 of which groove width is made larger than that of the ink chambers 22 as shown in ~~FIG. 6~~ FIGS. 6A – 6C).

The depth of the ink chambers 22 shown in FIG. 6C is 100 μm and each of the electrically conductive resin electrodes 11 is machined to a cross-sectional shape measuring 90 μm deep, in which the surface area of each electrically conductive resin electrode 11 is set to 3960 μm^2 which is larger than the area of each ink chamber 22. Therefore, it is possible to realize stable external circuit connections to external circuit leads 52 connected to driving IC 50 at low cost by using the inexpensive ACF 53. (See, FIGS. 7A – 7C) Also, the groove width is so large that the electrically conductive resin 10 can be filled with ease and an improvement in manufacturing yield can be realized in the process of filling the electrically conductive resin 10.